

ABSTRACT OF THE DISCLOSURE

A flip chip package comprises a carrier, a chip, a dam, a heat spreader, an underfill and a plurality of electrically conductive bumps. The chip is flip-chip bonded to the upper surface of the carrier. Furthermore, the dam is disposed on the carrier and supports the heat spreader. In addition, the underfill is filled into the space that is enclosed by the dam. In such a manner, the chip, the electrically conductive bumps and a portion of the carrier are covered by the underfill. The underfill is connected to the dam, the heat spreader and the carrier simultaneously, so the reinforced structure including the heat spreader, the underfill and the dam can reduce the stress at the interconnection between the chip and carrier so as to prevent the bumps connecting the chip and the carrier from being damaged.